



Excellence in Compliance Testing

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Re.: FCC ID: SDBGFL, IC: 2220A-GFL

To Whom It May Concern:

This application is being filed for a class II permissive change on the Sensus Metering Systems model GFL under the identifiers indicated above. The model GFL has three RF electrically identical variants, or printed circuit board configurations, all of which have been modified from the original and are included in this application. The characteristics which have degraded from those originally reported for certification were evaluated and are presented with this application. Modifications did not include changes the RF circuitry which remains identical to that originally reported. The following are the changes for each GFL variant:

2200-1216-01 - FlexNet 100G-FL PCB Changes:

- Added, D4, D5 and D6 clamping diodes on reed switch magnetic inputs for ESD protection.
- Q9 transistor which switches supply voltage to 12.8MHz TCXO changed from a BJT to MOSFET.
- Added U103, 16KBit SPI EEPROM for the pulses count.
- Added F1, 1.5A fuse between battery/HLC and boost converter for intrinsic safety
- Added test points for the reed switches
- Changed layout of PCB to allow on board Battery and HLC (Hybrid Layer Capacitor) instead of being external to package.

2200-1217-01 - FlexNet 300G-FL PCB Changes:

- A new onboard printed dipole type antenna replaced the onboard printed helical antenna on original endpoint.
- The antenna matching components changed with new antenna.
- Added, D4, D5 and D6 clamping diodes on reed switch magnetic inputs for ESD protection.
- Q9 transistor which switches supply voltage to 12.8MHz TCXO changed from a BJT to MOSFET.
- Added U103, 16KBit SPI EEPROM for the pulses count.
- Added F1, 1.5A fuse between battery/HLC and boost converter for intrinsic safety.
- Added test points for the reed switches
- Changed the spacing in between the remote option holes
- Changed layout of PCB to allow on board Battery and HLC (Hybrid Layer Capacitor) instead of being external to package.

2200-1218-01 - FlexNet 200G-FL PCB Changes:

- Added, D4, D5 and D6 clamping diodes on reed switch magnetic inputs for ESD protection.
- Q9 transistor which switches supply voltage to 12.8MHz TCXO changed from a BJT to MOSFET.
- Added U103, 16KBit SPI EEPROM for the pulses count.
- Added F1, 1.5A fuse between battery/HLC and boost converter for intrinsic safety
- Added test points for the reed switches
- Changed layout of PCB to allow on board Battery and HLC (Hybrid Layer Capacitor) instead of being external to package.

Sincerely,

Kirby Munroe
Director, Wireless Certifications
Advanced Compliance Solutions, Inc.